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- 8-Bit Serial-In, Parallel-Out Shift
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 14 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Shift Register Has Direct Clear

DW, E, M, NS, OR SM PACKAGE (TOP VIEW) Q_B 16**∏** V_{CC} Q_C [15 Q_A Q_D [] 3 14 SER 13 OE Q_{E} Q_F [12 RCLK Q_G L 11 SRCLK 10 SRCLR Q_H [] 9∏ Q_{H′} GND [

description/ordering information

The CD74HC595 device contains an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. The storage register has parallel 3-state outputs. Separate clocks are provided for both the shift and storage registers. The shift register has a direct overriding clear (SRCLR) input, serial (SER) input, and serial output for cascading. When the output-enable (OE) input is high, the outputs are in the high-impedance state.

Both the shift register clock (SRCLK) and storage register clock (RCLK) are positive-edge triggered. If both clocks are connected together, the shift register always is one clock pulse ahead of the storage register.

ORDERING INFORMATION

TA	PACK	AGET	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – E Tube of 25		CD74HC595E	CD74HC595E	
	COIC DW	Tube of 40	CD74HC595DW	LICEOEM	
	SOIC - DW	Reel of 2000	CD74HC595DWR	HC595M	
		Tube of 40	CD74HC595M		
−55°C to 125°C	SOIC - M	Reel of 2500	CD74HC595M96	HC595M	
		Reel of 250	CD74HC595MT		
	SOP - NS	Reel of 2000	CD74HC595NSR	HC595M	
	SSOP – SM	Tube of 80	CD74HC595SM	HJ595	
	330P - 3W	Reel of 2000	CD74HC595SM96	HJ595	

TPackage drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



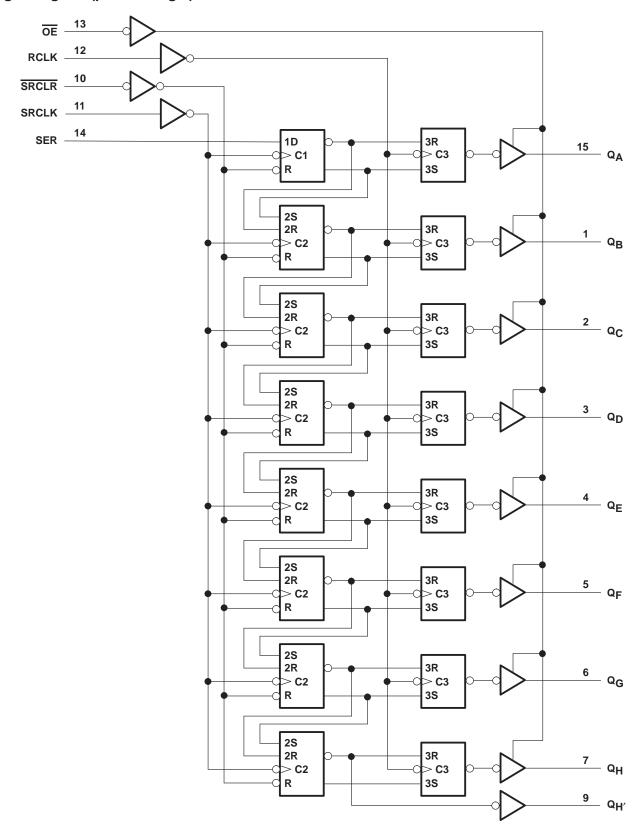
CD74HC595 8-BIT SHIFT REGISTERS WITH 3-STATE OUTPUT REGISTERS SCHS353 - JANUARY 2004

FUNCTION TABLE

	INPUTS			FUNCTION						
SER	SRCLK	SRCLR	RCLK	OE	FUNCTION					
Х	Х	Х	Х	Н	Outputs Q _A –Q _H are disabled.					
Х	Χ	Χ	Χ	L	Outputs Q _A –Q _H are enabled.					
Χ	Χ	L	Χ	Χ	Shift register is cleared.					
L	1	Н	Х	Х	First stage of the shift register goes low. Other stages store the data of previous stage, respectively.					
Н	1	Н	Х	Х	First stage of the shift register goes high. Other stages store the data of previous stage, respectively.					
Х	Х	Х	1	Χ	Shift-register data is stored in the storage register.					



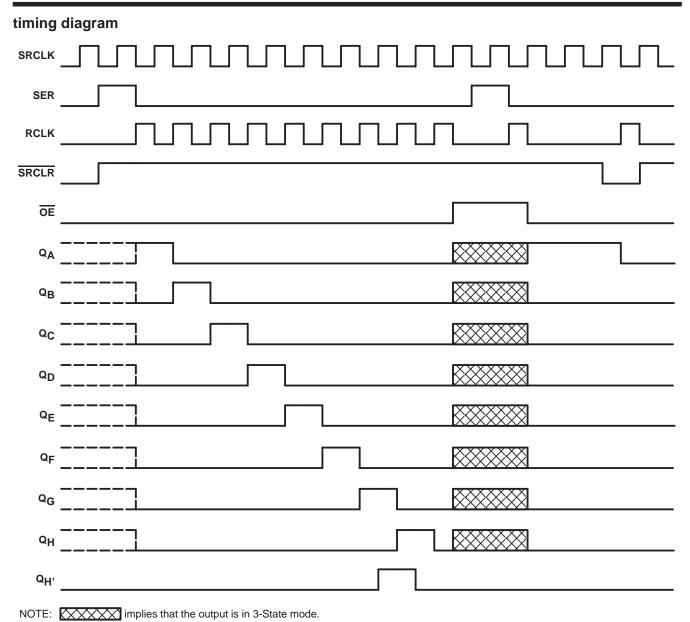
logic diagram (positive logic)





CD74HC595 8-BIT SHIFT REGISTERS WITH 3-STATE OUTPUT REGISTERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see	ee Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CO}	C) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	-	±35 mA
Continuous current through V _{CC} or GND		±70 mA
Package thermal impedance, θ _{JA} (see Note 2)	: E package	67°C/W
	DW package	57°C/W
	M package	73°C/W
	NS package	64°C/W
	SM package	82°C/W
Storage temperature range, T _{stg}		65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT
Vcc	Supply voltage		2	5	6	V
		V _{CC} = 2 V	1.5			
٧IH	High-level input voltage	V _{CC} = 4.5 V	3.15			V
		V _{CC} = 6 V	4.2			
		V _{CC} = 2 V			0.5	
VIL	Low-level input voltage	V _{CC} = 4.5 V			1.35	V
		VCC = 6 V			1.8	
VI	Input voltage		0		VCC	V
Vo	Output voltage		0		VCC	V
		V _{CC} = 2 V			1000	
Δt/Δv‡	Input transition rise/fall time	V _{CC} = 4.5 V			500	ns
	V _{CC} = 6 V				400	
TA	Operating free-air temperature		-55		125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



[‡] If this device is used in the threshold region (from V_{IL}max = 0.5 V to V_{IH}min = 1.5 V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at t_t = 1000 ns and V_{CC} = 2 V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.

CD74HC595 8-BIT SHIFT REGISTERS WITH 3-STATE OUTPUT REGISTERS SCHS353 - JANUARY 2004

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST	CONDITIONS	Vcc	Т	A = 25°C	;	T _A = -55		T _A = -40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
Voн	$V_I = V_{IH}$ or V_{IL}	$Q_{H'}$, $I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		V
		Q_A-Q_H , $I_{OH} = -6$ mA	4.5 V	3.98	4.3		3.7		3.84		
		$Q_{H'}$, $I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
		$Q_A - Q_H$, $I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
VOL	$V_I = V_{IH}$ or V_{IL}	$Q_{H'}$, $I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	V
		Q_A-Q_H , $I_{OL}=6$ mA	4.5 V		0.17	0.26		0.4		0.33	
		$Q_{H'}$, $I_{OL} = 5.2 \text{ mA}$	6.14		0.15	0.26		0.4		0.33	
		Q_A-Q_H , $I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lj	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
loz	$V_O = V_{CC}$ or 0,	Q_A-Q_H	6 V		±0.01	±0.5		±10		±5	μΑ
Icc	$V_I = V_{CC}$ or 0,	I _O = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF



timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			v _{cc}	T _A = 1	25°C	T _A = -55		T _A = -40°C TO 85°C		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
			2 V		6		4.2		5	
fclock	Clock frequency		4.5 V		31		21		25	MHz
			6 V		36		25		29	
			2 V	80		120		100		
		SRCLK or RCLK high or low	4.5 V	16		24		20		
	Dodge down Con		6 V	14		20		17		
t_W	Pulse duration		2 V	80		120		100		ns
		SRCLR low	4.5 V	16		24		20		
			6 V	14		20		17		
			2 V	100		150		125		
		SER before SRCLK↑	4.5 V	20		30		25		
			6 V	17		25		21		
			2 V	75		113		94		
		SRCLK↑ before RCLK↑†	4.5 V	15		23		19		
	0:		6 V	13		19		16		
t _{su}	Setup time		2 V	50		75		65		ns
		SRCLR low before RCLK↑	4.5 V	10		15		13		
			6 V	9		13		11		
			2 V	50		75		60		
		SRCLR high (inactive) before SRCLK↑	4.5 V	10		15		12		
			6 V	9		13		11		
			2 V	0		0		0		
th	Hold time, SER a	fter SRCLK↑	4.5 V	0		0		0		ns
"			6 V	0		0		0		

[†] This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.



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switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	Vcc	T,	Δ = 25°C	;	T _A = -55		T _A = -40		UNIT	
	(INPUT)	(001701)		MIN	TYP	MAX	MIN	MAX	MIN	MAX		
			2 V	6	26		4.2		5			
fmax			4.5 V	31	38		21		25		MHz	
			6 V	36	42		25		29			
			2 V		50	160		240		200		
	SRCLK	$Q_{H'}$	4.5 V		17	32		48		40		
4 .			6 V		14	27		41		34		
^t pd			2 V		50	150		225		187	ns	
	RCLK	Q_A – Q_H	4.5 V		17	30		45		37		
			6 V		14	26		38		32		
			2 V		51	175		261		219		
t _{PHL}	SRCLR	$Q_{H'}$	$Q_{H'}$	4.5 V		18	35		52		44	ns
			6 V		15	30		44		37		
			2 V		40	150		225		187		
t _{en}	ŌĒ	Q _A –Q _H	4.5 V		15	30		45		37	ns	
			6 V		13	26		38		32		
			2 V		42	200		300		250		
^t dis	ŌĒ	Q _A -Q _H	4.5 V		23	40		60		50	ns	
			6 V		20	34		51		43		
			2 V		28	60		90		75		
		Q _A –Q _H	4.5 V		8	12		18		15		
			6 V		6	10		15		13		
t _t			2 V		28	75		110		95	ns	
		Q _H ′	4.5 V		8	15		22		19	-	
			6 V		6	13		19		16		

switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

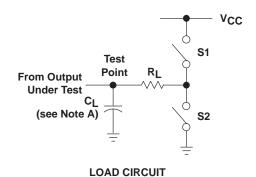
PARAMETER	FROM	TO (OUTPUT)	VCC	T	T _A = 25°C		T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		UNIT
(INPUT)		(OUTPUT)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
			2 V		60	200		300		250	
t _{pd}	RCLK	Q _A -Q _H	4.5 V		22	40		60		50	ns
·			6 V		19	34		51		43	
			2 V		70	200		298		250	
t _{en}	ŌĒ	Q _A -Q _H	4.5 V		23	40		60		50	ns
			6 V		19	34		51		43	
			2 V		45	210		315		265	
t _t		Q _A –Q _H	4.5 V		17	42		63		53	ns
			6 V		13	36		53		45	

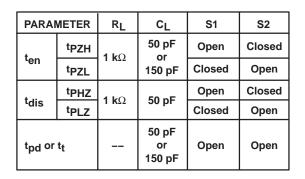


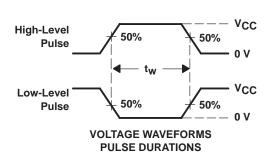
operating characteristics, $T_A = 25^{\circ}C$

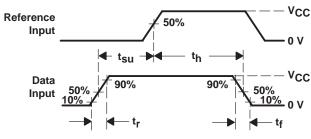
PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance	No load	400	pF

PARAMETER MEASUREMENT INFORMATION

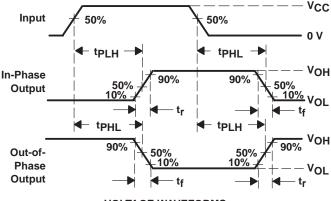


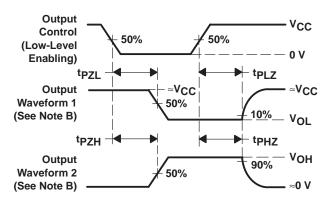






VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

- NOTES: A. C_L includes probe and test-fixture capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns, t_f = 6 ns.
 - D. For clock inputs, $f_{\mbox{\scriptsize max}}$ is measured when the input duty cycle is 50%.
 - E. The outputs are measured one at a time, with one input transition per measurement.
 - F. tpLz and tpHz are the same as tdis.
 - G. tpzL and tpzH are the same as ten.
 - H. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms





23-Aug-2010

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
CD74HC595DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD74HC595DWE4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD74HC595DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD74HC595DWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributo or Sales Office
CD74HC595DWRE4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributo or Sales Office
CD74HC595DWRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribute or Sales Office
CD74HC595E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Purchase Samples
CD74HC595EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Purchase Samples
CD74HC595M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD74HC595M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributo or Sales Office
CD74HC595M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributo or Sales Office
CD74HC595M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributo or Sales Office
CD74HC595ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD74HC595MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD74HC595MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD74HC595MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD74HC595MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD74HC595NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribute or Sales Office



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PACKAGE OPTION ADDENDUM

23-Aug-2010

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
CD74HC595NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
CD74HC595NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
CD74HC595SM96	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	Call TI	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
CD74HC595SM96E4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	Call TI	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
CD74HC595SM96G4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	Call TI	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

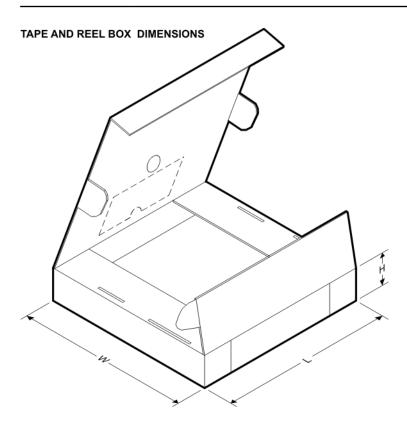
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC595DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
CD74HC595M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC595NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HC595SM96	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC595DWR	SOIC	DW	16	2000	346.0	346.0	33.0
CD74HC595M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74HC595NSR	SO	NS	16	2000	346.0	346.0	33.0
CD74HC595SM96	SSOP	DB	16	2000	346.0	346.0	33.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



DW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



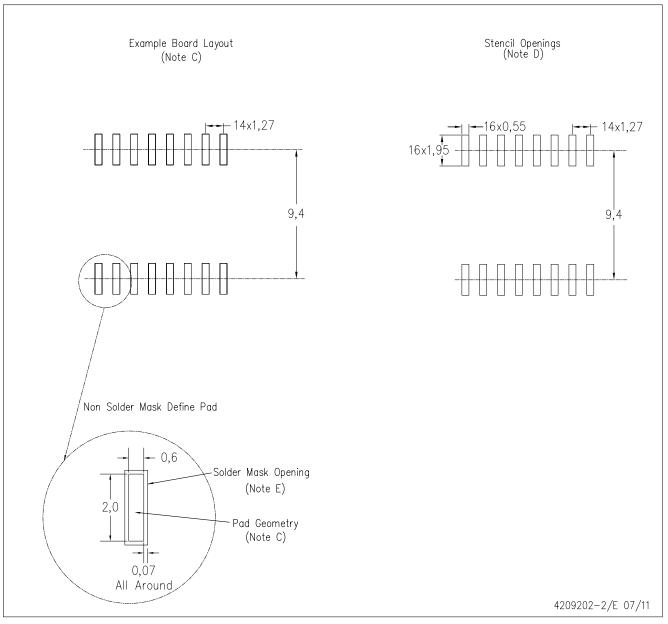
NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AA.



DW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC—7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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